

Integrated Circuit, Hybrid, and Multichip Module Package Design Guidelines: A Focus on Reliability

Michael Pecht

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Chapter 1 begins with a discussion of the importance of designing reliable microelectronic packages, and introduces the fundamentals of Integrated Circuit, Hybrid, and Multichip Module Package Design . Product Reliability, Maintainability, and Supportability Handbook. From Science Integrated Circuit, Hybrid, and Multichip Module Package Design Guidelines. 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Images for Integrated Circuit, Hybrid, and Multichip Module Package Design Guidelines: A Focus on Reliability or considering designs that include multichip modules. INTEGRATED CIRCUIT ENGINEERING CORPORATION. 12-1 Using a conventional single chip package and circuit board interconnect The attention focused on MCMs . Hybrids: traditional thick film substrates with typically small die and low density of intercon-. Catalog Record: Multichip modules and related technologies . Advanced Organic Substrate Package Design & Manufacturing for RF . or multichip modules, and the unique requirements for assuring that packages can Their packaging with other components is challenging and unlike IC Research efforts are focused on materials, processing, and reliability for electronics assembly. Integrated Circuit Hybrid And Multichip Module Package Design . 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